

This document refers to a box of technical reports in the Computer History Museum's collection, described under catalog number 102748610.

The following technical reports in this box have accompanying descriptions:

Competitive analysis of LSI NGINE module

"Analysis of the LSI NGINE module was performed to identify the materials and processes used in packaging and board, as well as the physical and thermal attributes of the module."

Materials analysis for Intel 80486 competitive analysis

"An analysis of the Intel i486 component was performed to identify the materials and processes used in chip interconnect and packaging, as well as the physical and thermal attributes of the component."

Achieving software usability a managers guide

"The aim of this book is to provide an overview of the methods that can easily be incorporated into the software development cycle to ensure that we in Digital produce products that meet the needs of users and that are easy to learn and easy to use."

Interlaminar stresses in layered beams

"An effective numerical procedure is developed for calculation of interlaminar shear and peeling stresses in layered beams. This procedure is based on the build-up-bar theory."